

L Number	Hits	Search Text	DB	Time stamp
1	1	("6630368").PN.	USPAT	2004/07/22 17:49
2	1		USPAT	2004/07/22 16:57
4	1510	257/686.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 17:51
5	1635	257/737.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 17:51
6	1256	257/777.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
7	1494	257/690.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
8	1083	257/691.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
9	1579	257/692.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
10	1635	257/737.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
11	659	257/776.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
12	605	257/782.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
13	1693	257/784.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:29
14	1564	257/786.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:30
17	12655	257/\$6.cccls. and ((die or chip or (integrated adj circuit)) and (dicing or cutting or cut) and (lead or leads or wires or wire or electrodes))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:44
18	5836	257/\$6.cccls. and ((die or chip or (integrated adj circuit)) and ((dicing or cutting or cut) SAME (lead or leads or wires or wire or electrodes)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/07/22 18:44

19	3596	257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) SAME (lead or leads or wires or wire or electrodes)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 18:45
20	2363	257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 18:45
21	80	(257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))) and oblique	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 18:50
22	479	(257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))) and (angles or angle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 18:50
23	436	((257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))) and (angles or angle)) not ((257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))) and oblique)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 18:57
24	2283	(257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes))) not ((257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))) and oblique)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 18:57
25	1847	((257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes))) not ((257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))) and oblique)) not ((257/\$6.cccls. and ((die or chip or (integrated adj circuit)) same ((dicing or cutting or cut) WITH (lead or leads or wires or wire or electrodes)))) and (angles or angle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 18:58